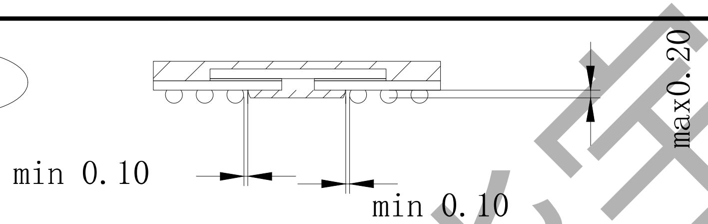
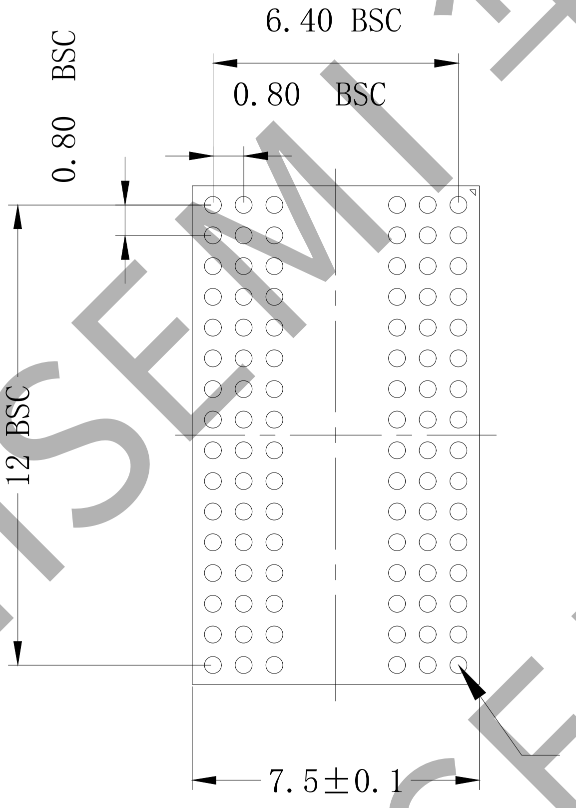
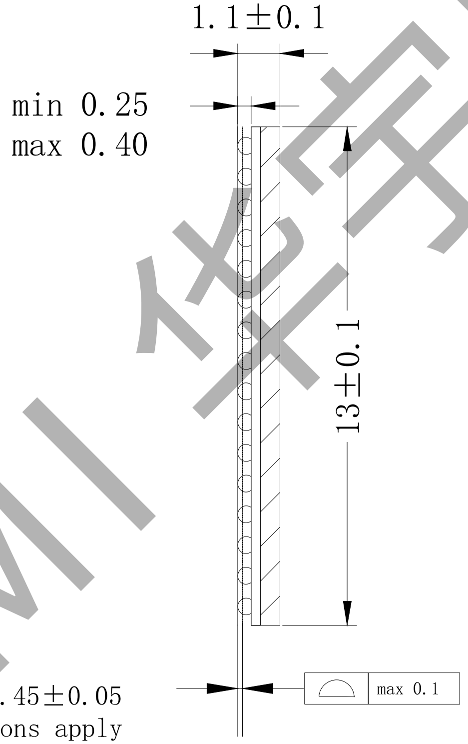
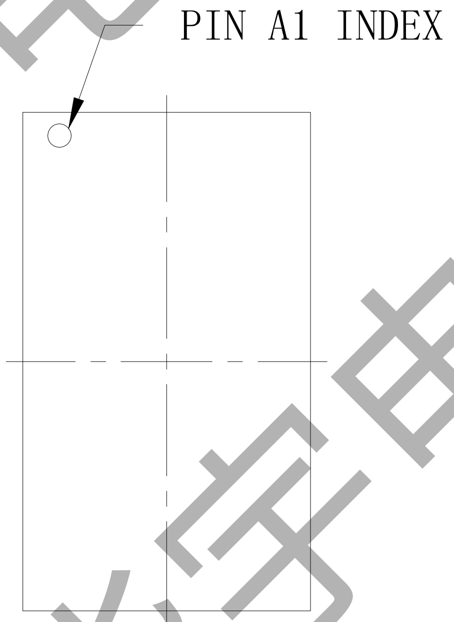
RoSH



履历		
序号	内容	时间
1	新发行	2025.10.13
2	更新客户单颗设计	2025.11.26







96 XΦ0.45±0.05
Dimensions apply
to solder balls
post re-flow on
Φ0.42 SMD ball
pad.

确认签字回传

QUALITY SPECIFICATION	
ITEM	SPEC. (mm)
Mold Thickness	0.5100
Substrate Thickness	0.2400
Ball Size	0.4500

POD

(SCALE =8:1)

产品图

华宇电子		PROJECTION			
TITLE: SUBSTRATE DRAWING [基板图] FBGA-7.5X13 240X77.5-1BLOCK			DRAWING NO. SO-FBGA96(075130)XXX001		REV. REV.
SIZE	PAGE	UNIT	DIMENSION AND TOLERANCES		SCALE
A3	1/5	MM	ASME Y14.5M		SCALE

SIGNATURE AREA

DESIGN	
CHECK	
DESIGN APPROVE	
PROCESS	
STAND.	
APPROVE	

FORMAT CODE: A